SPECIFICATION

REFOND P/N

RF-A2T29-W6SE-A8

□ R&D

■ Mass Production

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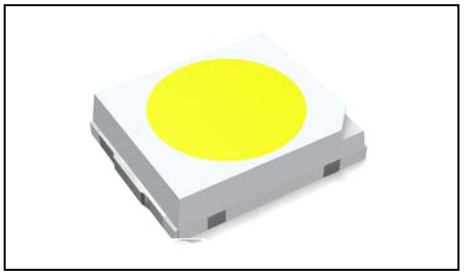
1. Description

1.1 General Description



The white LED, which was fabricated by using a blue chip and the phosphor.

Product Package:2.80mmX3.50mmX0.80mm.

LED :2.80mmX3.50mmX0.80mm

1.2 Features

►PLCC2 Package. PLCC2

►Extremely wide viewing angle.

►Suitable for all SMT assembly and solder process. SMT

►Available on tape and reel.

►Moisture sensitivity level: Level 2. Level2

►Compliance with RoHS and REACH. RoHS REACH

► Qualifications: The product qualification test plan is based on the guidelines of AEC-Q102 Stress Test Qualification for Automotive Grade Discrete Semiconductors :

AEC-Q102

1.3 Application

►Automotive Lighting Interior and Exterior.

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1.4 Package Dimension

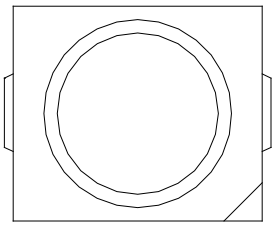

Fig.1–1 Top View

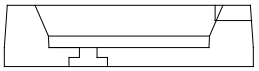

Fig.1–2 Side View

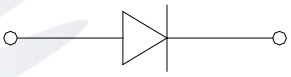

Fig.1–3 Bottom View

Fig.1–4 Polarity

Fig.1–5 Soldering Pattern

Notes

1. All dimensions units are millimeters.

2. All dimensions tolerances are 0.2mm unless otherwise noted. ±0.2

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Notes

1. 1/10 Duty cycle, 10

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Fig. 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-4

BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4	
VM1	0.3150	0.2995	0.3115	0.3212	0.3268	0.3371	0.3282	0.3162	
VM2	0.3210	0.3060	0.3190	0.3280	0.3340	0.3420	0.3340	0.3230	
VM3	0.3270	0.3140	0.3270	0.3360	0.3420	0.3490	0.3410	0.3300	0.3410

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1.7 Typical Optical Characteristics C u r v e s

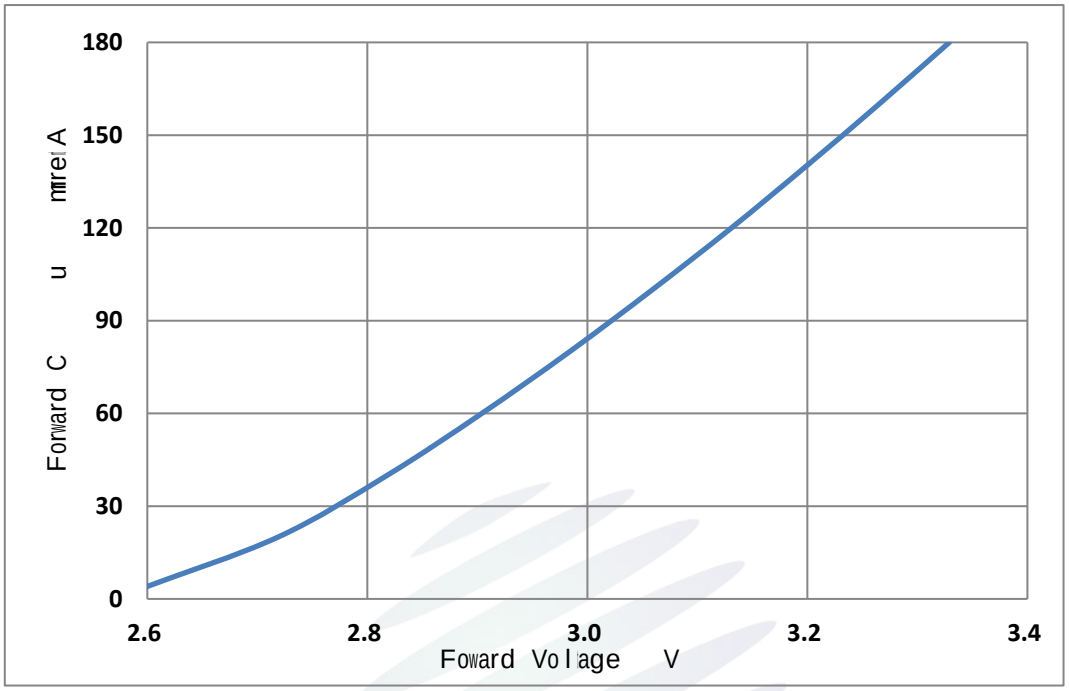

Fig. 1-7 Forward Voltage Vs Forward Current

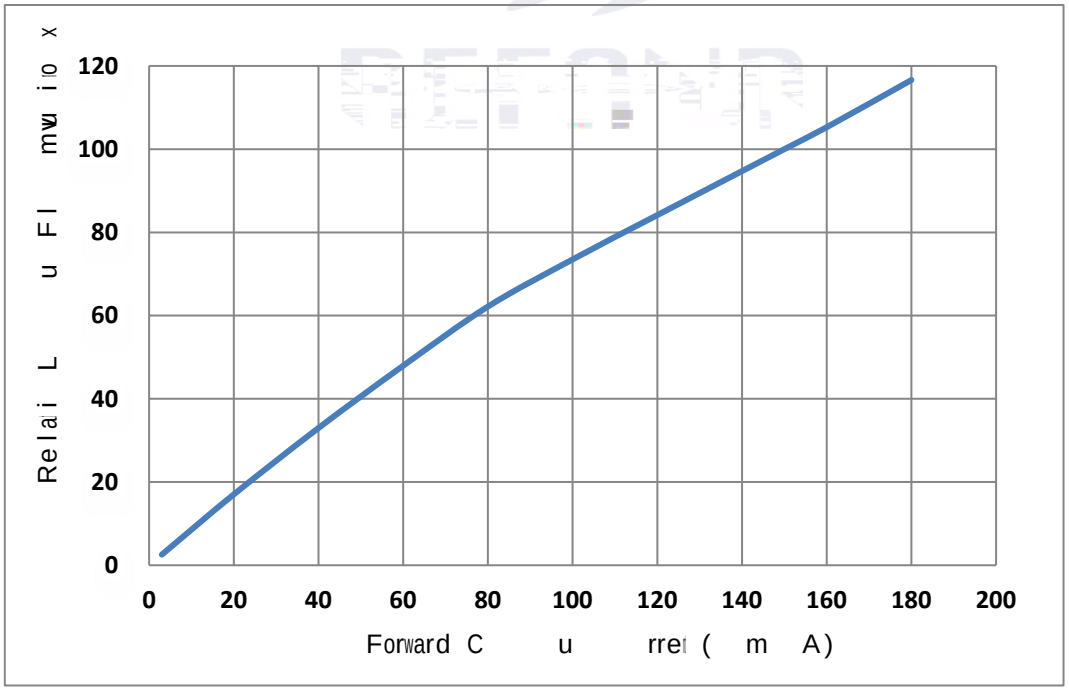

Fig. 1-8 Forward Current Vs Relative Intensity

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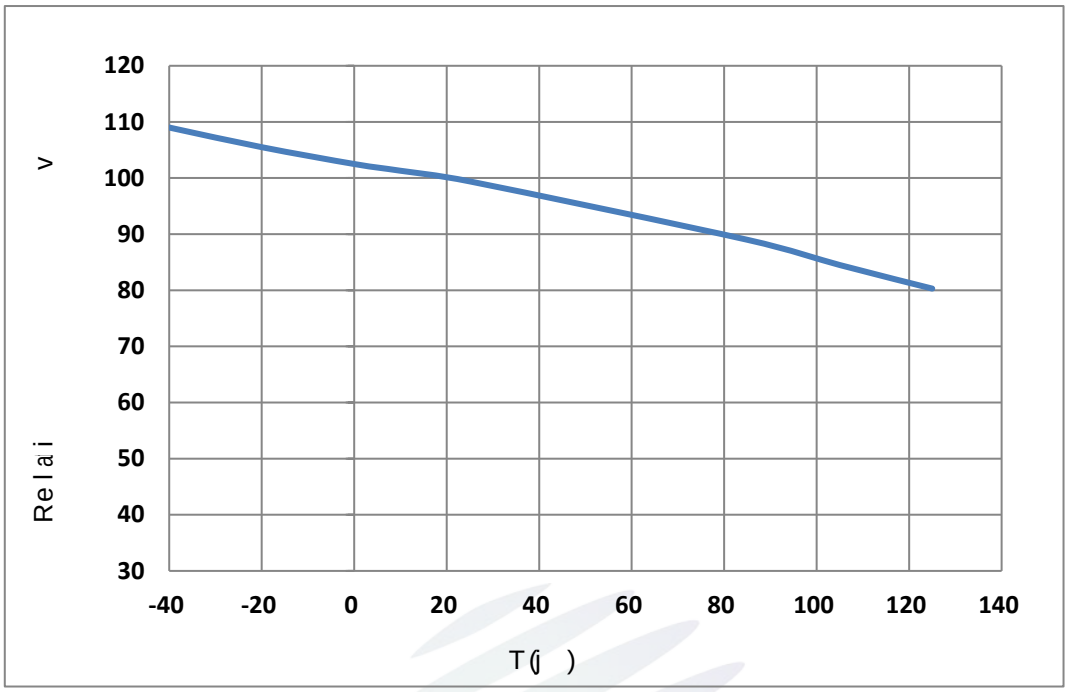

Fig. 1-9 Junction Temperature Vs Relative Luminous Flux

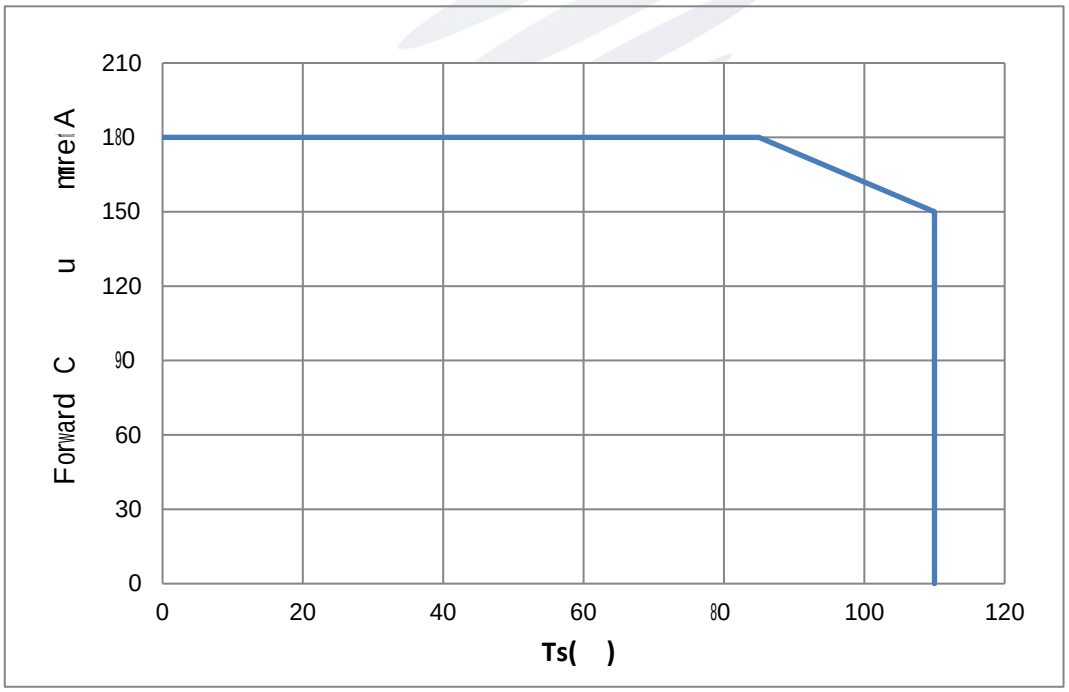

Fig. 1-10 Solder Temperature Vs Forward Current

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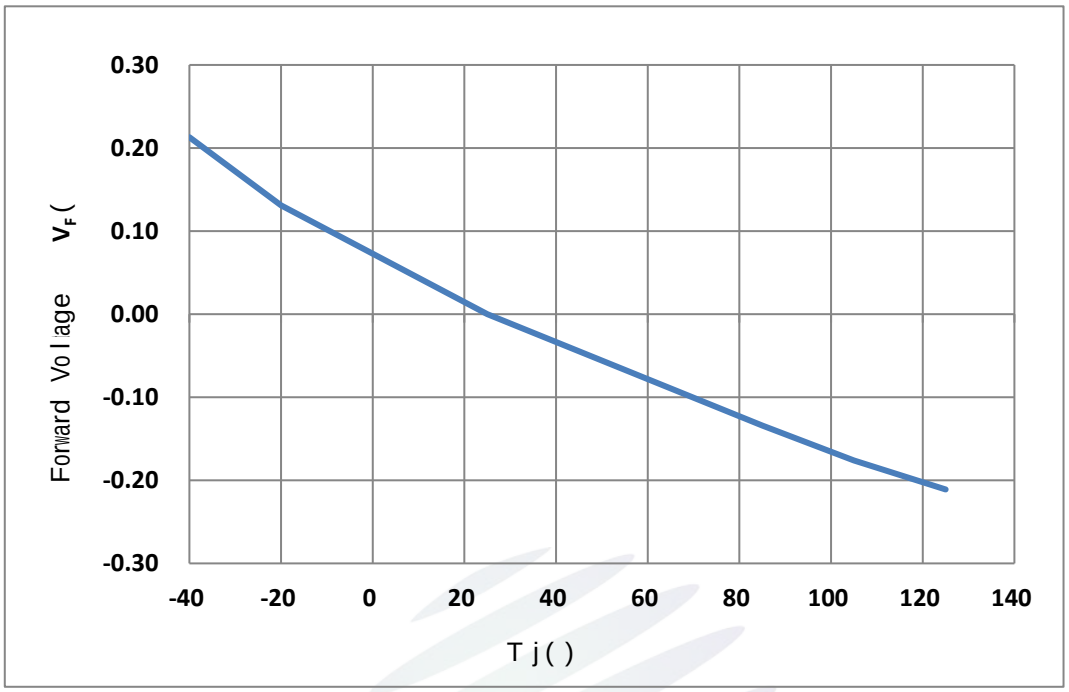

Fig. 1-11 Voltage Shift Vs Junction Temperature

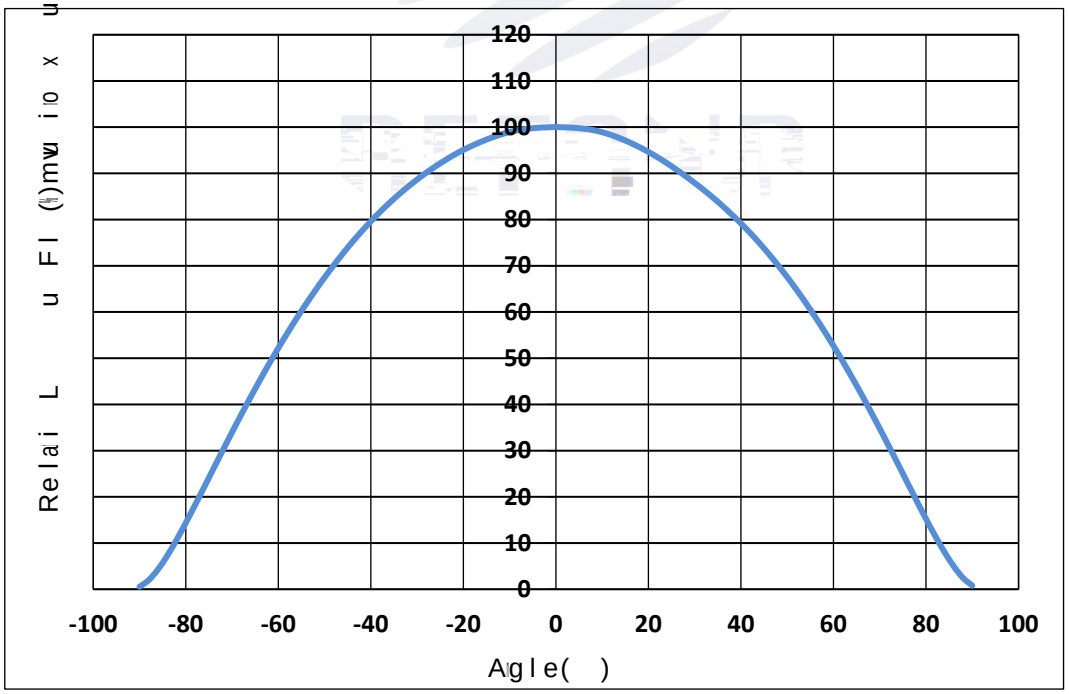

Fig. 1-12 Radiation diagram

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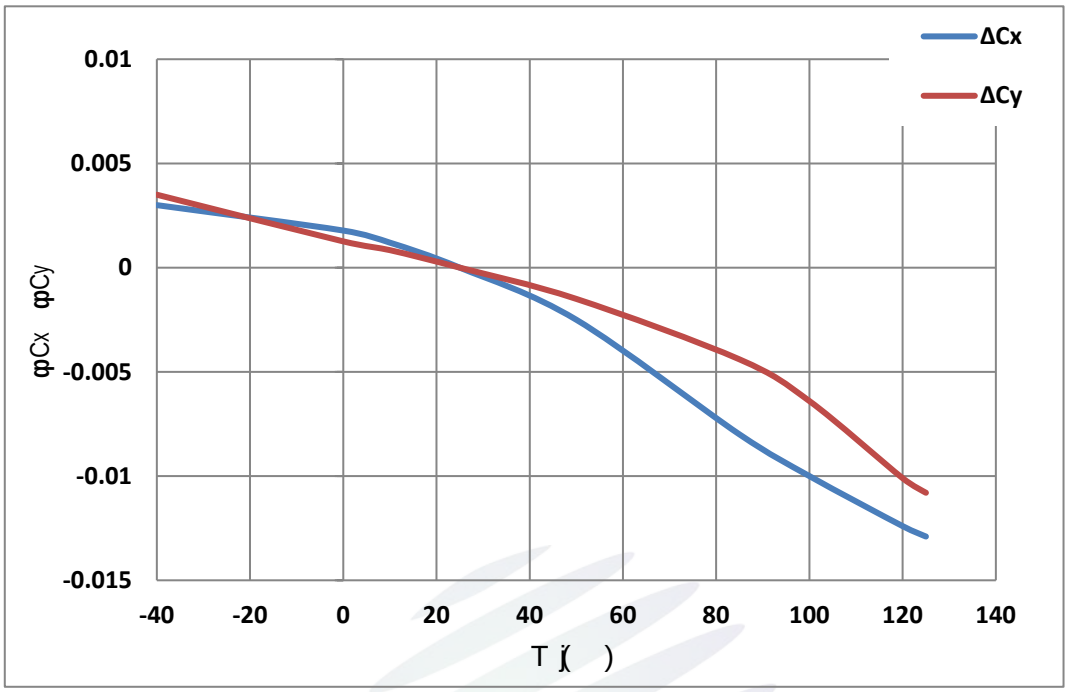

Fig. 1-13 Chromaticity Coordinate Vs Solder Temperature

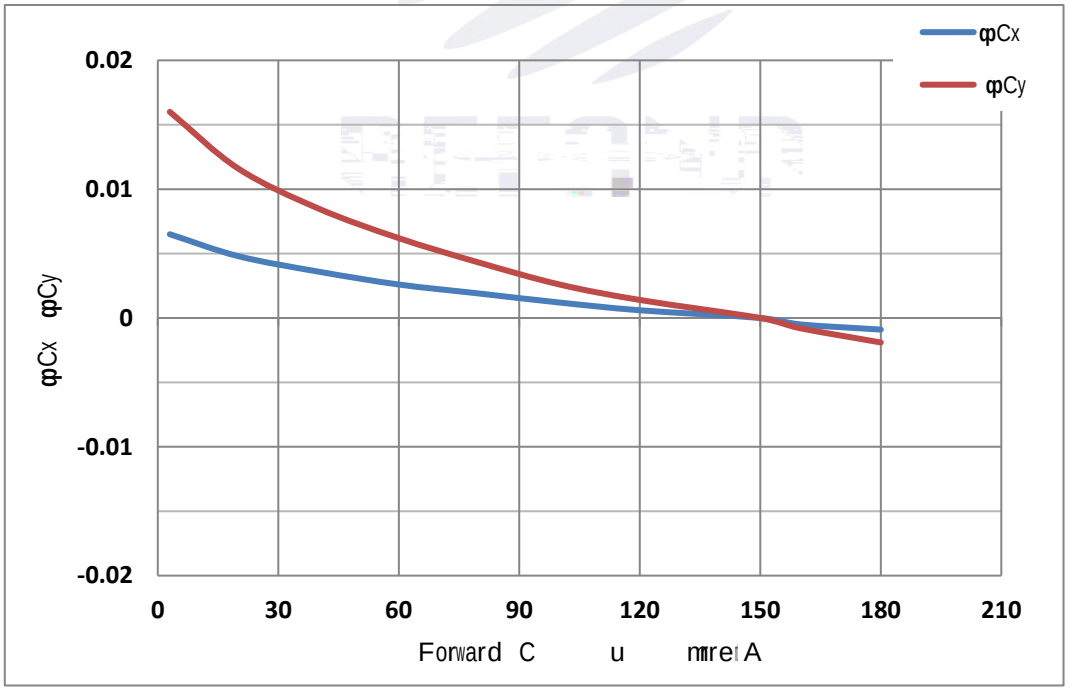

Fig. 1-14 Chromaticity Coordinate Shift Vs Forward Current

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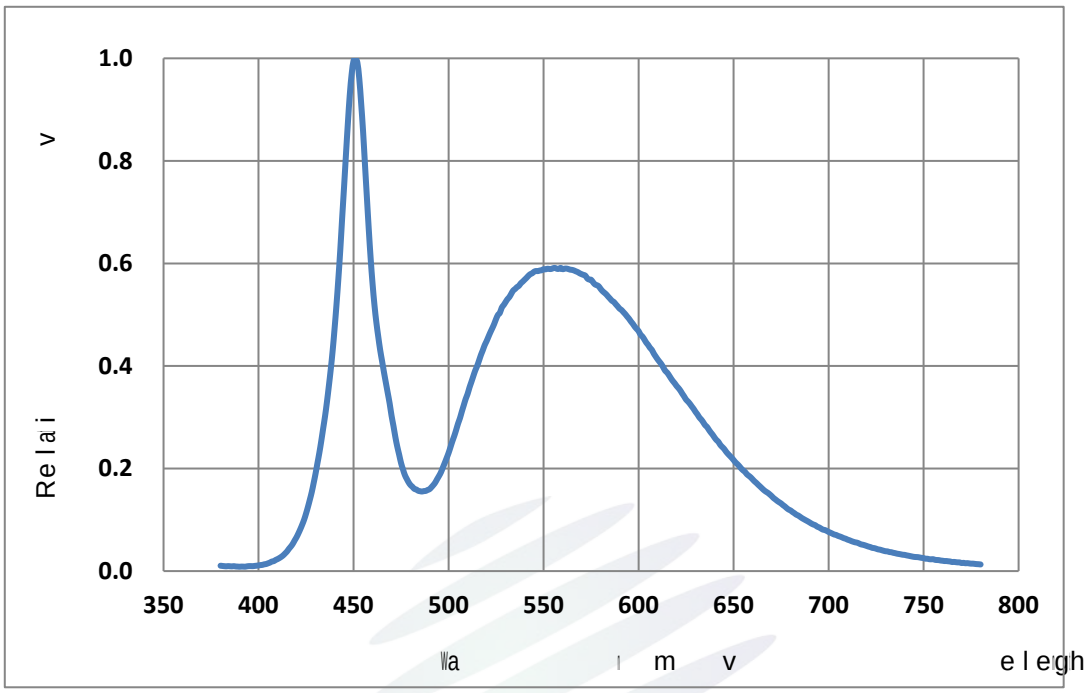

Fig. 1-15 Spectrum Distribution

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2. Packaging

2.1 Packaging Specification

Package:4000pcs/reel. 4000pcs

2.1.1Carrier Tape Dimension

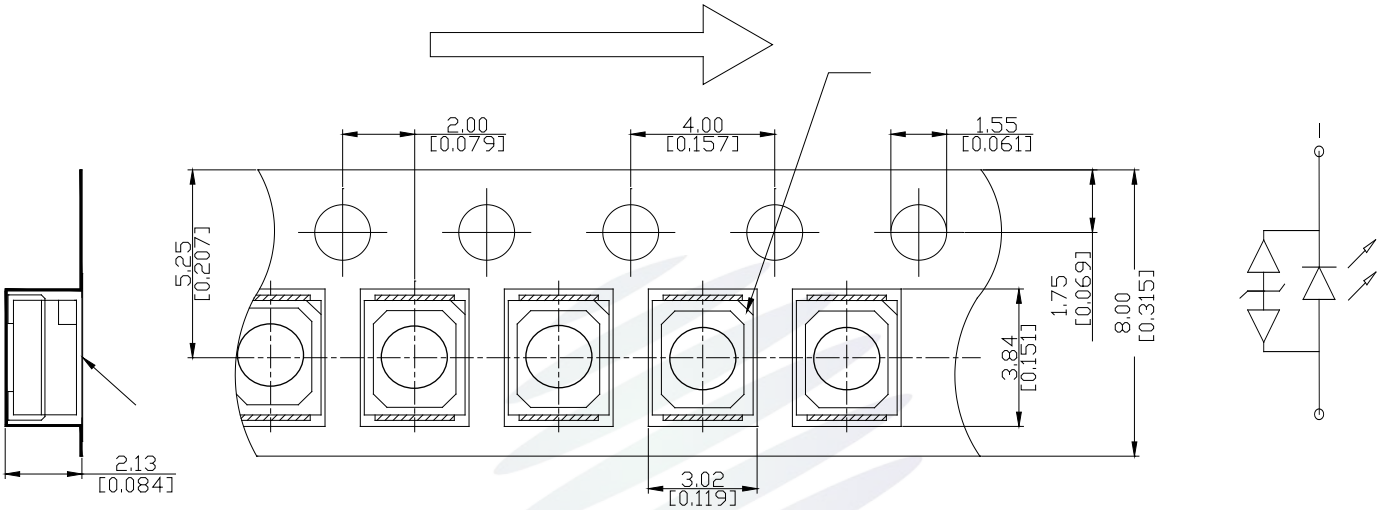

Fig.2-1 Carrier Tape Dimension

2.1.2Reel Dimension

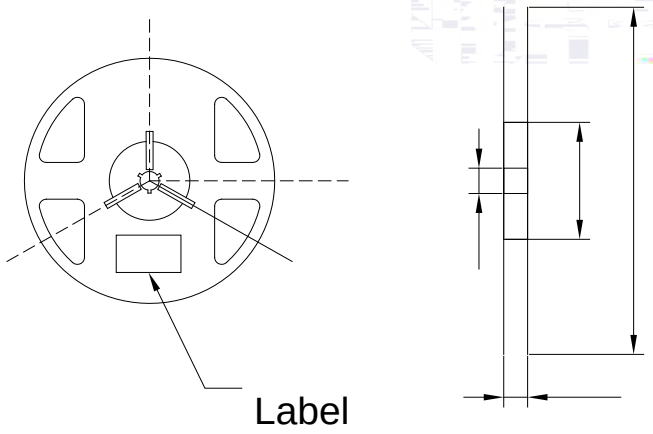

Fig.2-2 Reel Dimension

Table 2-1 Reel Dimension

A	8.0 ± 0.1mm
B	178 ± 1mm
C	60 ± 1mm
D	13.0 ± 0.5mm

Notes

The tolerances unless mentioned ±0.1mm. Unit : mm ± 0.1

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2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re
Reflow	JESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
MSL2 2	JESD22-A113	85 / 60%RH	168 hrs.	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min ↑↓10s 125 15min	1000 cycle	20pcs.	0/1
Life Test	JESD22-A108	Ta=105 I_F=150mA	1000hrs.	20pcs.	0/1
High Temperature High Humidity Life Test	JESD22-A101	85 / 85%RH I_F=150mA	1000hrs.	20pcs.	0/1

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2.5 Criteria For Judging Damage

Table 2-4Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	I_F=150mA	-	U.S.L*)x1.1
Reverse Current	I_R	V_R = 5V	-	U.S.L*)x2.0
Luminous Flux	Φ	I_F=150mA	L.S.L*)x0.7	-

Notes

1.U.S.L: Upper standard level L.S.L: Lower standard level

2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others. / LED

LED

3. The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

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Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings ,LED will be damaged. 24 LED

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED LED

3.1.2 Cautions

The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED PCB

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

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4. Handling Precautions

4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement.LED

LED 100PPM.

(2) In order to prevent ex-ternal material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM,the single content of Chlorine elementis required to be less than 900PPM,the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. LED LED

900PPM 900PPM

1500PPM.

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify compatibility, Refond recommends that all chemicals and materials be tested in the specific application and environment for which they are intended to be used. Attaching LEDs, do not use adhesives that outgas organic vapor. LED

LED LED

LED

(4) Handle the component along the side surface by using forceps or appropriate tools; Do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.

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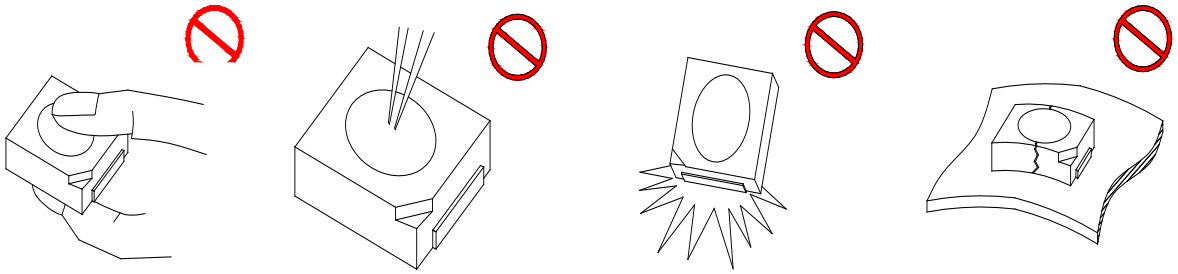

Fig 4-1Cautions

(5) In designing a circuit,the current through each LED can not exceed the absolute maximum rating specified for each LED.In the mean while,resistors for protection should be applied,other wise slight voltage shift will cause big current change,burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF.If the reverse voltage is applied to LED, migration can be generated resulting in LED damage. LED

LED

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline,such as brightness decreased,Color change and so on.Please consider the heat generation of the LEDs when making the system design.LED LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust,requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED

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Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	≤ 30	≤ 75%	Within 1 Year From Date
	After Opening Aluminum Bag	≤ 30	≤ 60%	Recommended for use within 24 hours 24
Baking		60 ± 5	-	≥ 24hours 24

(8) If the moisture absorbent material silica gel has faded away or the LEDs have exceeded the storage time,baking treatment should be performed after unpacking and based on the following condition 60 5

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Declare

This specification is written both in English and in Chinese and the latter is formal.

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